



Technical Data  
Data Sheet N0769, Rev. -

*Green Products*

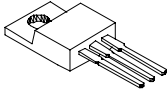
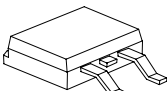
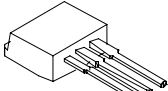
**MBR30200CT / MBRB30200CT / MBR30200CT-1**  
**SCHOTTKY RECTIFIER**

**Applications:**

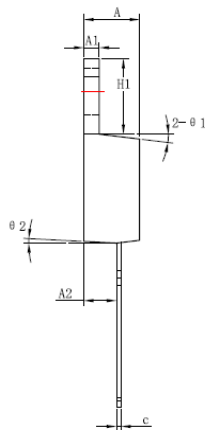
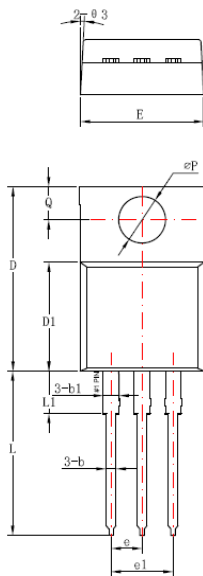
- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

**Features:**

- 150 °C T<sub>J</sub> operation
- Center tap configuration
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Case styles		
<b>MBR30200CT</b>	<b>MBRB30200CT</b>	<b>MBR30200CT-1</b>
		
<b>TO-220AB</b>	<b>D<sup>2</sup>PAK</b>	<b>TO-262</b>

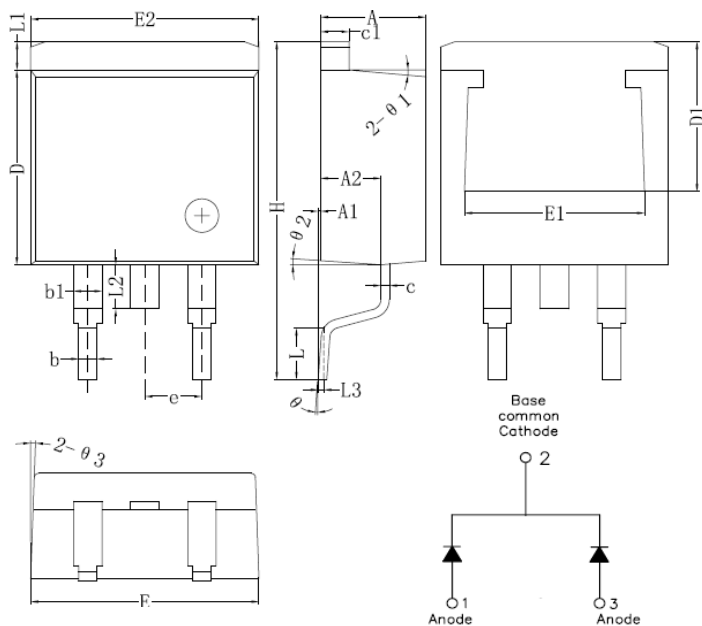
**Mechanical Dimensions: In Inches / mm**



Symbol	Dimensions in millimeters		
	Min	Typical	Max
A	4.42	4.57	4.72
A1	1.17	1.27	1.37
A2	2.59	2.69	2.89
b	0.71	0.81	0.96
b1		1.27	
c	0.36	0.38	0.61
D	14.94	15.24	15.54
D1	8.85	9.00	9.15
E	10.01	10.16	10.31
e		2.54	
e1		5.06	
H1	6.04	6.24	6.44
L	12.7	13.56	13.78
L1		3.5	
ΦP	3.74	3.84	4.04
Q	2.54	2.74	2.94
Ø1		7°	
Ø2		3°	
Ø3		4°	

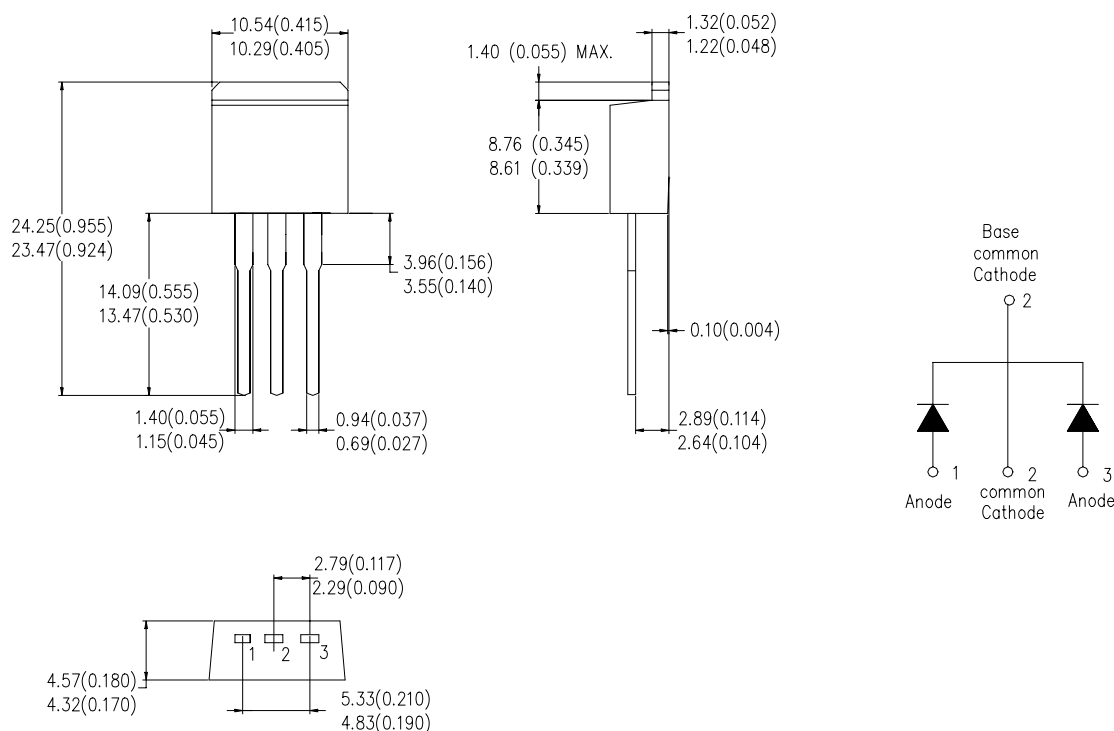
**TO-220AB**

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• FAX (86) 25-87123900 • World Wide Web Site - <http://www.sangdest.com.cn> • E-Mail Address - [sales@sangdest.com.cn](mailto:sales@sangdest.com.cn) •



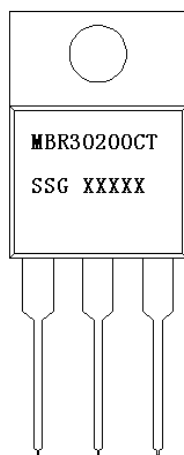
**D<sup>2</sup>PAK**

Symbol	Dimensions in millimeters		
	Min.	Typical	Max.
A	4.55	4.70	4.85
A1	0	0.10	0.25
A2	2.59	2.69	2.89
b	0.71	0.81	0.96
b1		1.27	
c	0.36	0.38	0.61
c1	1.17	1.27	1.37
D	8.55	8.70	8.85
D1	6.40		
E	10.01	10.16	10.31
E1	7.6		
E2	9.98	10.08	10.18
e		2.54	
H	14.6	15.1	15.6
L	2.00	2.30	2.70
L1	1.17	1.27	1.40
L2			2.20
L3		0.25BSC	
e	0	-	8°
e1		5°	
e2		4°	
e3		4°	

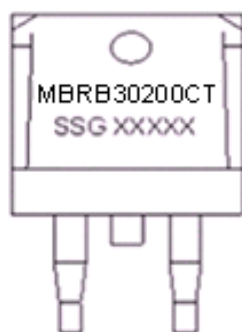


**TO-262**

**Marking Diagram:**



MBR30200CT



MBRB30200CT

Where XXXXX is YYWWL

MBR = Device Type  
 B = Package type  
 30 = Forward Current (30A)  
 200 = Reverse Voltage (200V)  
 CT/CT-1 = Configuration  
 SSG = SSG  
 YY = Year  
 WW = Week  
 L = Lot Number

**Cautions:** Molding resin  
 Epoxy resin UL:94V-0

**Ordering Information:**

Device	Package	Shipping
MBR30200CT	TO-220AB (Pb-Free)	50pcs / tube
MBRB30200CT	D <sup>2</sup> PAK (Pb-Free)	800pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

**Maximum Ratings:**

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	$V_{RWM}$	-	200	V
Average Forward Current(per device)	$I_{F(AV)}$	50% duty cycle @ $T_C = 133^\circ\text{C}$ , rectangular wave form	30	A
Peak Repetitive Forward Current(per leg)	$I_{FRM}$	Rated $V_R$ square wave, 20KHz $T_C = 133^\circ\text{C}$	20	A
Peak One Cycle Non-Repetitive Surge Current (per leg)	$I_{FSM}$	8.3 ms, half Sine pulse	150	A

**Electrical Characteristics:**

Characteristics	Symbol	Condition	Max.	Units
Forward Voltage Drop (per leg) *	$V_{F1}$	@ 15 A, Pulse, $T_J = 25\text{ }^\circ\text{C}$	0.90	V
	$V_{F2}$	@ 15 A, Pulse, $T_J = 125\text{ }^\circ\text{C}$	0.70	V
Reverse Current (per leg) *	$I_{R1}$	@ $V_R = \text{rated } V_R$ $T_J = 25\text{ }^\circ\text{C}$	1.0	mA
	$I_{R2}$	@ $V_R = \text{rated } V_R$ $T_J = 125\text{ }^\circ\text{C}$	6.0	mA
Junction Capacitance (per leg)	$C_T$	@ $V_R = 5\text{V}$ , $T_C = 25\text{ }^\circ\text{C}$ $f_{SIG} = 1\text{MHz}$	400	pF
Voltage Rate of Change	dv/dt	-	10,000	V/ $\mu\text{s}$

\* Pulse Width < 300 $\mu\text{s}$ , Duty Cycle <2%

**Thermal-Mechanical Specifications:**

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	$T_J$	-	-55 to +150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-	-55 to +150	$^\circ\text{C}$
Maximum Thermal Resistance Junction to Case	$R_{\theta JC}$	DC operation	2.0	$^\circ\text{C/W}$
Maximum Thermal Resistance, Case to Heat Sink	$R_{\theta JA}$	DC operation	50	$^\circ\text{C/W}$
Maximum Thermal Resistance, Case to Heat Sink	$R_{\theta CS}$	Mounting surface, smooth and greased	0.50	$^\circ\text{C/W}$
Approximate Weight	wt	-	2	g
Case Style	TO-220AB D <sup>2</sup> PAK TO-262			

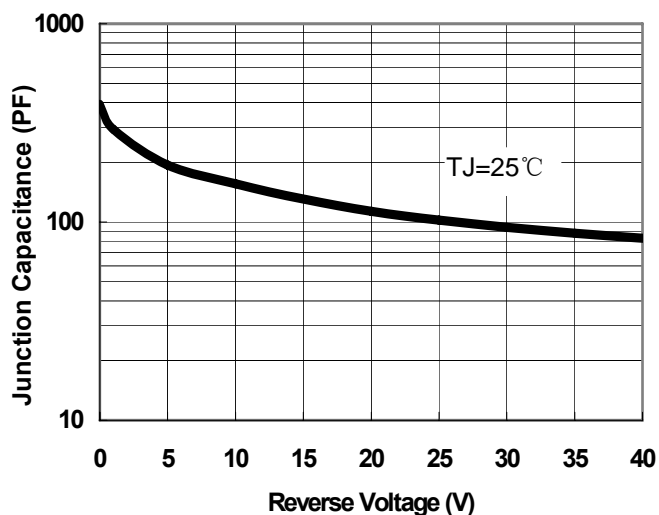


Fig.1-Typical Junction Capacitance

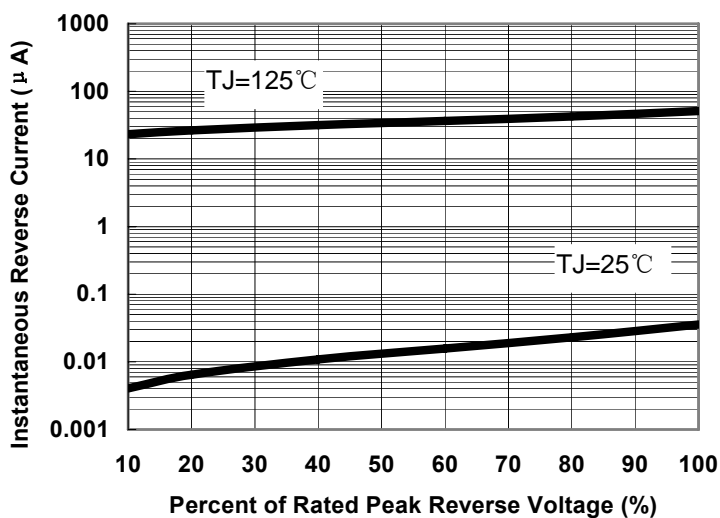


Fig.2-Typical Reverse Characteristics

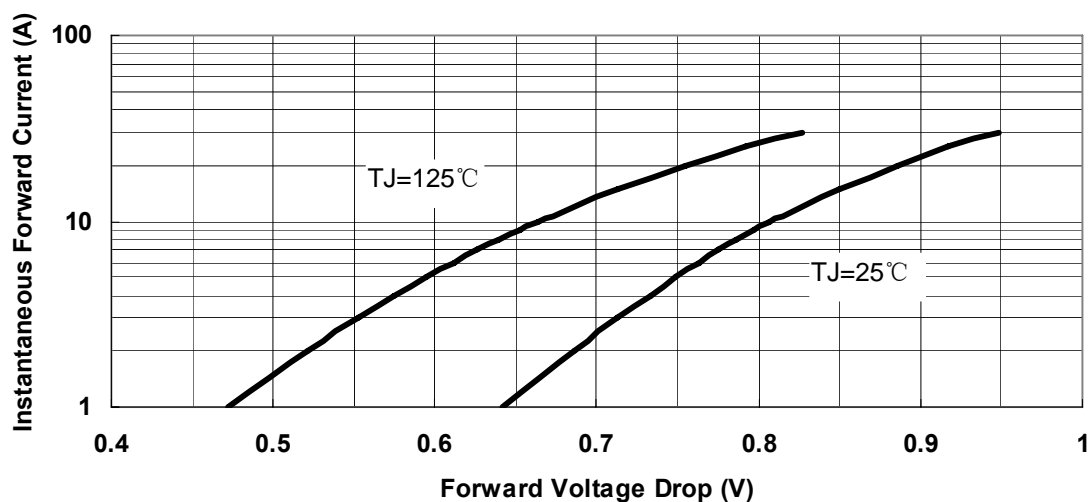


Fig.3-Typical Instantaneous Forward Voltage Characteristics

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